

PENDING CLAIMS:

1-2. (Canceled)

3. (Previously Presented) An apparatus comprising:

- a) a substrate support;
- b) a first edge ring disposed on the substrate support, the first edge ring having one or more tapered recesses; and
- c) a second edge ring having one or more matching tapered pins for mating engagement with the one or more tapered recesses of the first edge ring, wherein the first edge ring comprises a purge ring.

4. (Previously Presented) An apparatus comprising:

- a) a substrate support;
- b) a first edge ring disposed on the substrate support, the first edge ring having one or more tapered recesses; and
- c) a second edge ring having one or more matching tapered pins for mating engagement with the one or more tapered recesses of the first edge ring, wherein the second edge ring comprises a shadow ring.

5. (Previously Presented) An apparatus comprising:

- a) a substrate support;
- b) a first edge ring disposed on the substrate support, the first edge ring having one or more tapered recesses; and
- c) a second edge ring having one or more matching tapered pins for mating engagement with the one or more tapered recesses of the first edge ring, wherein the first edge ring includes one tapered recess and one diametrically positioned tapered slot, and wherein the second edge ring includes two tapered pins diametrically positioned for mating engagement with the recess and the slot.

6. (Previously Presented) The apparatus of claim 3, wherein the substrate support comprises a purge gas channel.
7. (Canceled)
8. (Previously Presented) An apparatus for processing substrates, comprising:
 - a) a chamber;
 - b) a substrate support disposed in the chamber;
 - c) a first edge ring disposed on the substrate support, the first edge ring having one or more tapered recesses; and
 - d) a second edge ring having one or more matching tapered pins for mating engagement with the one or more tapered recesses of the first edge ring, further comprising:
 - e) a chamber body ring disposed on an interior surface of the chamber, the chamber body ring having one or more recesses for supporting engagement with the second edge ring.
9. (Original) The apparatus of claim 8 wherein the first edge ring includes one or more slots disposed for mating engagement with the one or more tapered pins on the second edge ring.
10. (Original) The apparatus of claim 8 wherein the first edge ring comprises a purge ring.
11. (Original) The apparatus of claim 8 wherein the second edge ring comprises a shadow ring.
12. (Original) The apparatus of claim 8 wherein the first edge ring includes one tapered recess and one diametrically positioned tapered slot, and wherein the second edge ring includes two tapered pins diametrically positioned for mating engagement with the recess and the slot.

13. (Original) The apparatus of claim 8 wherein the substrate support comprises a purge gas channel, and the first edge ring comprises a purge ring.

14. (Original) The apparatus of claim 8 wherein the one or more recesses on the chamber body ring include tapered side surfaces.

15-16. (Canceled)

17. (Previously Presented) A method for supporting a substrate in a chamber, comprising:

a) positioning the substrate on a substrate support having a first edge ring disposed around a substrate supporting surface, the first edge ring having one or more recesses; and

b) positioning a second edge ring above the first edge ring, wherein the second edge ring has one or more pins for mating engagement with the one or more recesses on the first edge ring, and wherein the first edge ring comprises a purge ring.

18. (Previously Presented) A method for supporting a substrate in a chamber, comprising:

a) positioning the substrate on a substrate support having a first edge ring disposed around a substrate supporting surface, the first edge ring having one or more recesses; and

b) positioning a second edge ring above the first edge ring, wherein the second edge ring has one or more pins for mating engagement with the one or more recesses on the first edge ring wherein the second edge ring comprises a shadow ring.

19. (Previously Presented) A method for supporting a substrate in a chamber, comprising:

a) positioning the substrate on a substrate support having a first edge ring disposed around a substrate supporting surface, the first edge ring having one or more recesses; and

b) positioning a second edge ring above the first edge ring, wherein the second edge ring has one or more pins for mating engagement with the one or more recesses on the first edge ring wherein the first edge ring includes one tapered recess and one diametrically positioned tapered slot, and wherein the second edge ring includes two tapered pins diametrically positioned for mating engagement with the recess and the slot.

20. (Previously Presented) A method for supporting a substrate in a chamber, comprising:

a) positioning the substrate on a substrate support having a first edge ring disposed around a substrate supporting surface, the first edge ring having one or more recesses;

b) positioning a second edge ring above the first edge ring, wherein the second edge ring has one or more pins for mating engagement with the one or more recesses on the first edge ring; and

c) flowing a purge gas around the substrate during substrate processing.

21. (Previously Presented) An apparatus for processing a substrate, comprising:

a substrate support having a surface contacting a first surface of a substrate;

a purge ring disposed on the substrate support, the purge ring having one or more tapered recesses; and

a shadow ring having one or more matching tapered pins for mating engagement with the one or more tapered recesses of the shadow ring, wherein the shadow ring overhangs a portion of a second surface of the substrate and the second surface of the substrate is opposite the first surface of the substrate.

22. (Previously Presented) The apparatus of claim 21, further comprising a chamber body ring disposed on an interior surface of the chamber, the chamber body

ring having one or more recesses for supporting engagement with the second edge ring.

23. (Previously Presented) The apparatus of claim 22, wherein the one or more recesses on the chamber body ring comprise tapered side surfaces.

24. (Previously Presented) The apparatus of 21, wherein the purge ring further comprises one or more slots disposed for mating engagement with the one or more tapered pins on the shadow ring.

25. (Previously Presented) The apparatus of claim 24, wherein the purge ring comprises one tapered recess and one diametrically positioned tapered slot, and wherein the shadow ring comprises two tapered pins diametrically positioned for mating engagement with the tapered recess and the tapered slot.